

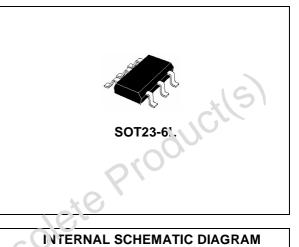
P-CHANNEL 20V - 0.065Ω - 5A SOT23-6L 2.5V-DRIVE STripFET™ II POWER MOSFET

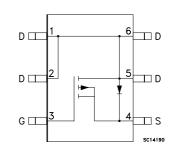
TYPE	V _{DSS}	R _{DS(on)}	I _D
STT5PF20V	20 V	< 0.080 Ω (@4.5V) < 0.10 Ω (@2.5V)	5 A

- TYPICAL R_{DS}(on) = 0.065Ω (@4.5V)
- TYPICAL R_{DS}(on) = 0.085Ω (@2.5V)
- ULTRA LOW THRESHOLD GATE DRIVE (2.5V)
- STANDARD OUTLINE FOR EASY AUTOMATED SURFACE MOUNT ASSEMBLY

DESCRIPTION

This Power MOSFET is the latest development of STMicroelectronics unique "Single Feature SizeTM" strip-based process. The resulting transistor shows extremely high packing density for low on-resistance.





APPLICATIONS

- MOBILE PHONE APPLICATIONS
- DC-DC CONVERTERS
- BATTERY MANAGEMENT IN NOMADIC EQUIPMENT

ORDERING INFORMATION

SALES TYPE	MARKING	PACKAGE	PACKAGING
STT5PF20V	STPN	SOT23-6L	TAPE & REEL

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{DS}	Drain-source Voltage (V _{GS} = 0)	20	V
V _{DGR}	Drain-gate Voltage (R_{GS} = 20 k Ω)	20	V
V _{GS}	Gate- source Voltage	± 8	V
Ι _D	Drain Current (continuous) at T _C = 25°C	5	A
ID	Drain Current (continuous) at T _C = 100°C	3.1	A
I _{DM} (•)	Drain Current (pulsed)	20	А
P _{TOT}	Total Dissipation at $T_C = 25^{\circ}C$	1.6	W

(•) Pulse width limited by safe operating area Note: For the P-CHANNEL MOSFET actual polarity of voltages and current has to be reversed

THERMAL DATA

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	DATA	×	51
Rthj-amb	Thermal Resistance Junction-ambient Max	78	°C/W
Tj	Max. Operating Junction Temperature	150	°C
T _{stg}	Storage Temperature	-55 tr, 150	°C

ELECTRICAL CHARACTERISTICS (TJ = 25 °C UNLESS OTHER WISE SPECIFIED) OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _(BR) DSS	Drain-source Breakdown Voltage	$I_{\rm D} = 250 \ \mu\text{A}, \ V_{\rm G3} = 0$	20			V
IDSS	Zero Gate Voltage	V _{DS} = Max Rating			1	μA
	Drain Current (V _{GS} = 0)	V_{DS} = Max Rating, T _C = 125 °C			10	μA
I _{GSS}	Gate-body Leakage Current (V _{DS} = 0)	$V_{GS} = \pm 8V$			±100	nA
ON (1)	prov					
Symbol	Parameter	Test Conditions	Min.	Tvp.	Max.	Unit

ON (1)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _{GS(ti})	Cate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	0.45			V
RD(;(or,)	Static Drain-source On	$V_{GS} = 4.5 V$, $I_D = 2.5 A$		0.065	0.080	Ω
5	Resistance	$V_{GS} = 2.5 V$, $I_D = 2.5 A$		0.085	0.10	Ω

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
g _{fs} (1)	Forward Transconductance	$V_{DS} = 15 \text{ V}, I_D = 2.5 \text{ A}$		6.6		S
C _{iss}	Input Capacitance	$V_{DS} = 15 \text{ V}, \text{ f} = 1 \text{ MHz}, \text{ V}_{GS} = 0$		412		pF
Coss	Output Capacitance			179		pF
C _{rss}	Reverse Transfer Capacitance			42.5		pF

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ELECTRICAL CHARACTERISTICS (CONTINUED) SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{d(on)}	Turn-on Delay Time	V _{DD} = 10 V, I _D = 2.5 A		11		ns
t _r	Rise Time	$R_G = 4.7\Omega V_{GS} = 2.5 V$ (see test circuit, Figure 1)		47		ns
Q _g Q _{gs} Q _{gd}	Total Gate Charge Gate-Source Charge Gate-Drain Charge	$\label{eq:VDD} \begin{array}{l} V_{DD} = 10 \text{ V}, I_D = 5 \text{ A}, \\ V_{GS} = 2.5 \text{ V} \\ (\text{see test circuit, Figure 2}) \end{array}$		4.5 0.73 1.75		nC nC nC

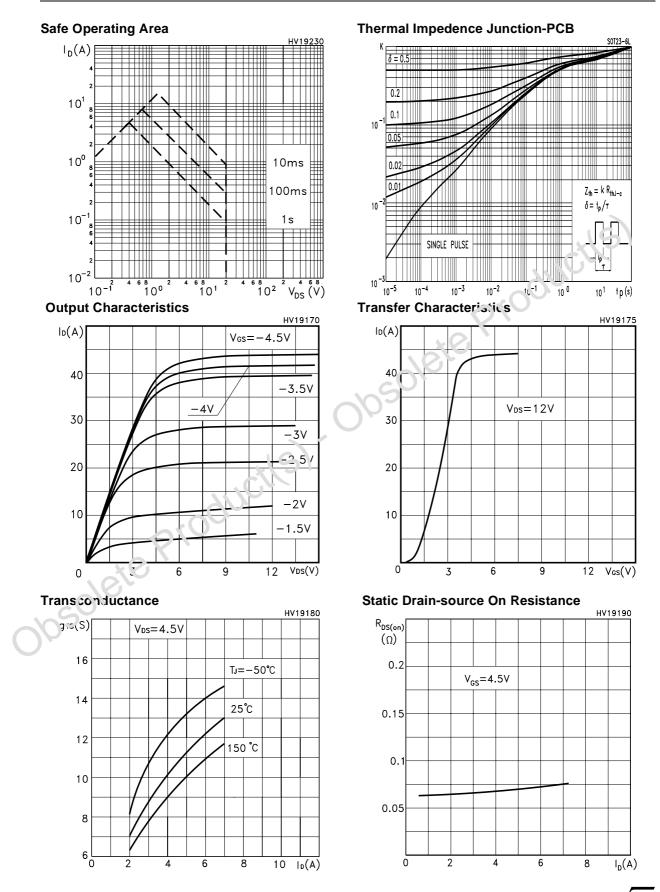
SWITCHING OFF

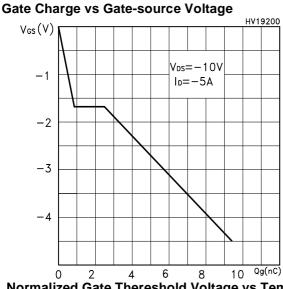
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{d(off)} t _f	Turn-off-Delay Time Fall Time	$V_{DD} = 10 \text{ V}, \text{ I}_D = 2.5 \text{ A},$ $R_G = 4.7\Omega, \text{ V}_{GS} = 2.5 \text{ V}$ (see test circuit, Figure 1)		38 20	d	ns
SOURCE D		Toot Conditions		<u> </u>	Max	11

SOURCE DRAIN DIODE

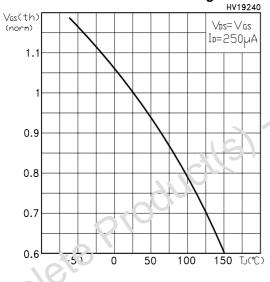
	Test Conditions	۸. 'n	Тур.	Max.	Unit
ce-drain Current		0		5	Α
ce-drain Current (pulsed	d)			20	Α
ard On Voltage	I _{SD} = 5 A, V _{GS} = 0			1.2	V
erse Recovery Time erse Recovery Charge erse Recovery Current	I _{SD} = 5 A, di/c ⁺ - 100 õs, V _{DD} = 16 √, i ₁ = 150°C (see test circr∴t, Figure 3)		32 12.8 0.8		ns nC A
AUC					
Prov					
Pro					90



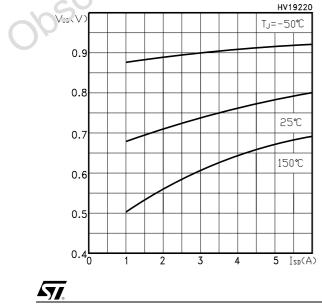




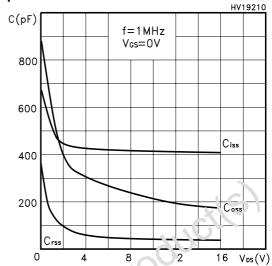
Normalized Gate Thereshold Voltage vs Temp.



Source-thain Diode Forward Characteristics



Capacitance Variations



Normalized On Resistance vs Temperature

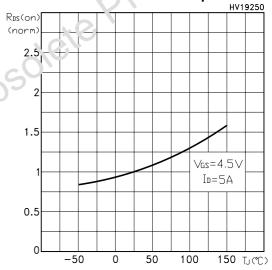


Fig. 1: Switching Times Test Circuit For Resistive Load

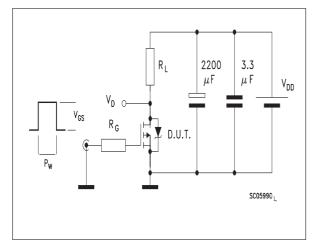


Fig. 3: Test Circuit For Diode Recovery Behaviour

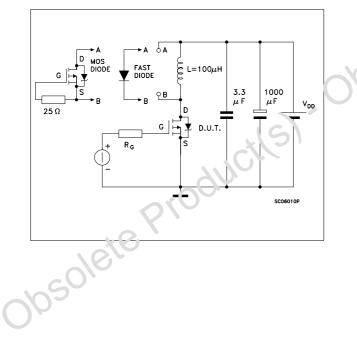
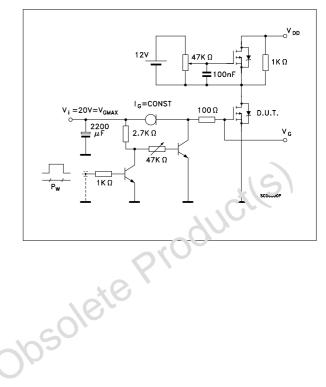
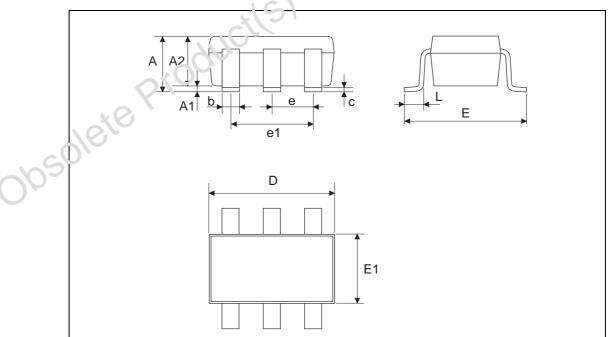


Fig. 2: Gate Charge test Circuit



DIM.		mm			mils			
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.		
А	0.90		1.45	0.035		0.057		
A1	0.00		0.15	0.000		0.006		
A2	0.90		1.30	0.035		0.051		
b	0.25		0.50	0.010		0.020		
С	0.09		0.20	0.004		0.008		
D	2.80		3.10	0.110	00	0.122		
E	2.60		3.00	0.102		0.118		
E1	1.50		1.75	0.058	1	0.069		
L	0.35		0.55	0.014		0.022		
е		0.95	00.		0.037			
e1		1.90			0.075			

TSOP-6 MECHANICAL DATA



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